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### **ACCEPTED MANUSCRIPT**

# Enhancement of Evaporative Heat Transfer on Carbon Nanotube Sponges by Electric Field Reinforced Wettability

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**KEYWORDS.** Carbon Nanotube Sponges; Superhydrophobicity; Superhydrophilicity; Evaporation Heat Transfer; Electrowetting.

**ABSTRACT.** Phase-change thermal management devices are the most effective approach to managing the increasing redundant heat in integrated electronic chips. The cooling performance

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